Schottky Barrier Diode

### DB2G32500L1

# **Panasonic**

### DB2G32500L1

#### For rectification

#### ■ Features

- Low forward voltage VF
- Forward current (Average) IF(AV) ≦ 1.0 A rectification is possible
- RoHS compliant (EU RoHS / MSL:Level 1 compliant)

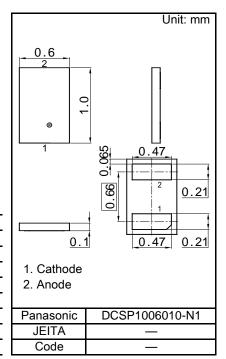
■ Marking Symbol: D3

### Packaging

Embossed type (Thermo-compression sealing): 1 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Reverse Voltage *1	VR	-	30	V
Maximum Peak Reverse Voltage *1	VRM	-	30	V
Average Forward Current *2,3	IF(AV)	-	1.0	Α
Average Forward Current *2,4	IF(AV)	-	1.0	Α
Non-repetitive Peak Surge Forward Current *1,5	IFSM	-	15	Α
Operating Junction Temperature *6	Tj	-	150	°C
Ambient Temperature	Та	-40	+150	°C
Storage Temperature	Tstg	-55	+150	°C



Note) \*1: Ta = Tj = 25°C

\*2: Squre wave :  $\sigma$  = 0.5

\*3: Ta ≦ 103°C, when device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (620.0mm² area, 36μm thick).

- \*4: Tsp ≦ 139°C
- \*5: Squre wave : Tp = 5 ms
- \*6: Power derating is necessary so that Tj < 150°C.

(Waveform definition)	IF <b>↑</b> ← Tp
Duty Cycle : $\sigma = \frac{Tp}{T}$	Time
	Time

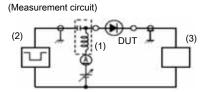
#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward Voltage	VF	IF = 1.0 A	-	0.39	0.48	V
Reverse Current	IR	VR = 30 V	-	60	300	μA
Terminal Capacitance	Ct	VR = 10 V, f = 1 MHz	-	34	-	pF
Reverse Recovery Time *1	trr	IF = IR = 100 mA, Irr = 10 mA	-	10.3	-	ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.).

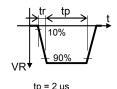
Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. \*1: Measurement circuit, input pulse, output pulse for Reverse recovery time



(1) Bias Insertion Unit (N-50BU)

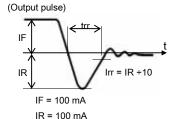
- (2) Pulse Generator (PG-10N), RS =  $50 \Omega$
- (3) Wave Form Analyzer (SAS-8130), Ri = 50  $\Omega$



(Input pulse)

tr = 0.35 ns

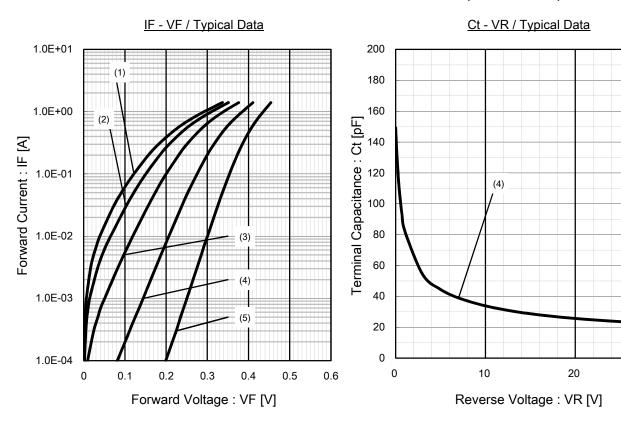
 $\sigma = 0.05$ 



Irr = 10 mA

Established: 2015-10-13 Revised

## Electrical Characteristics Technical Data (Reference)



1.0E-01
1.0E-02
1.0E-03
1.0E-04
1.0E-05
1.0E-06
1.0E-07
1.0E-08
1.0E-09
0 10 20 30

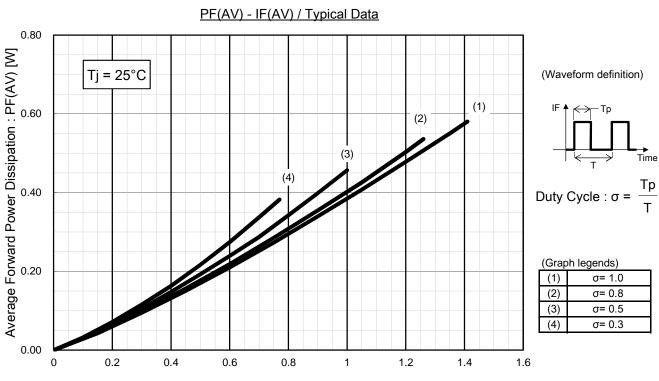
Reverse Voltage: VR [V]

(Grap	h legen	ds)		
(1)	Ta =	150	°C	
(2)	Ta =	125	°C	
(3)	Ta =	85	°C	
(4)	Ta =	25	°C	
(5)	Ta =	-40	°C	

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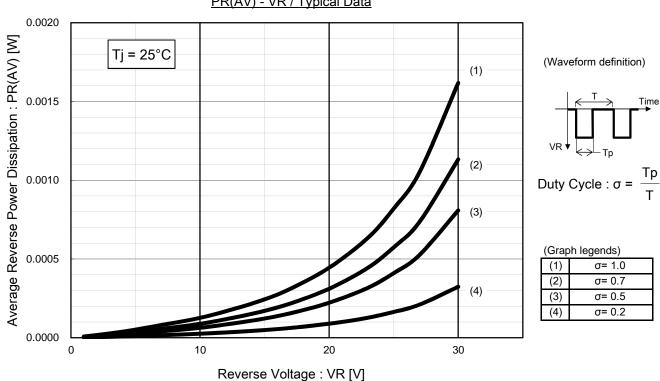
30

### Electrical Characteristics Technical Data (Reference)



Average Forward Current: IF(AV) [A]

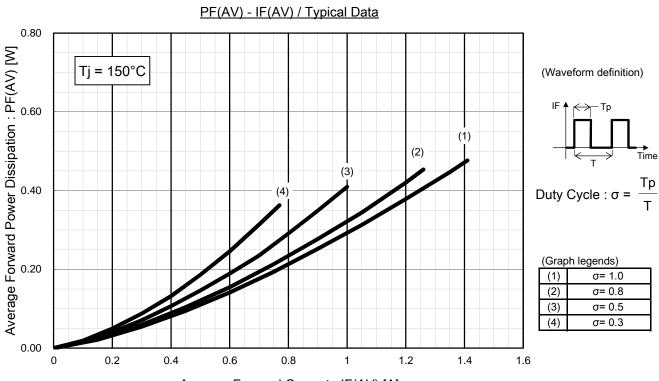
# PR(AV) - VR / Typical Data



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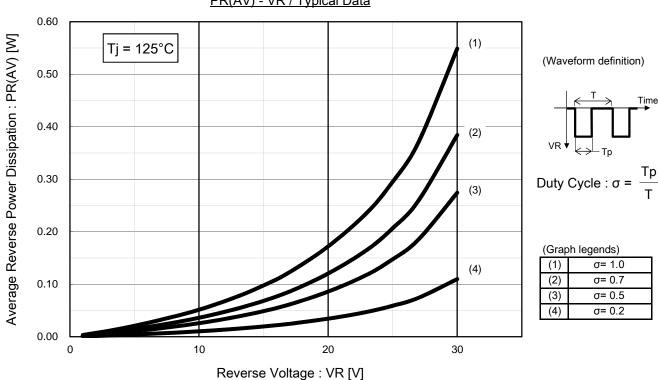
Established: 2015-10-13

### Electrical Characteristics Technical Data (Reference)



Average Forward Current: IF(AV) [A]

### PR(AV) - VR / Typical Data



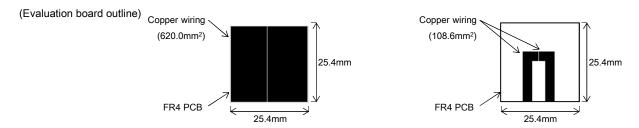
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Established: 2015-10-13

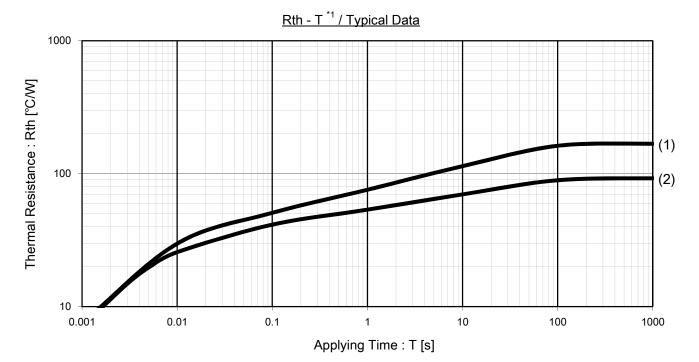
#### ■ Thermal Characteristics

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Thermal Resistance, Junction to Solder Point	$R_{th(j-sp)}$	Ta = 25°C, in free air	-	20	1	°C/W
Thermal Resistance, Junction to Ambient *1	R <sub>th(j-a)</sub>	Ta = 25°C, in free air	-	92	ı	°C/W
Thermal Resistance, Junction to Ambient *2	$R_{th(j-a)}$	Ta = 25°C, in free air	-	170	-	°C/W

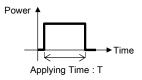
- Note) \*1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (620.0mm² area, 36µm thick).
  - \*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.6mm² area, 36µm thick).



### Thermal Characteristics Technical Data (Reference)



Note) \*1: Single pulse measurement (Waveform definition)



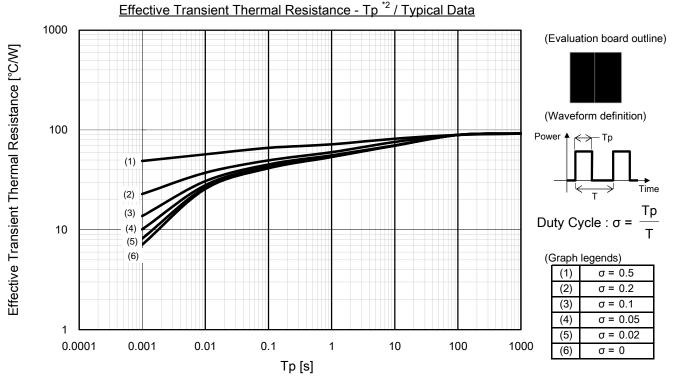
(Graph legends)

-		0 ,
	(1)	Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick),
(1)		copper wiring (108.6mm <sup>2</sup> area, 36µm thick).
ĺ	(2)	Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick),
(	(2)	copper wiring (620.0mm <sup>2</sup> area, 36µm thick).

### DB2G32500L1

### Thermal Characteristics Technical Data (Reference)

#### Effective Transient Thermal Resistance - Tp \*1 / Typical Data 1000 (Evaluation board outline) Effective Transient Thermal Resistance [°C/W] (Waveform definition) 100 Power **↑** ← Tp (1) (2)(3) (4) Duty Cycle : σ = 10 (5) (6)(Graph legends) $\sigma = 0.5$ $\sigma = 0.2$ $\sigma = 0.1$ $\sigma = 0.05$ 1 $\sigma = 0.02$ 0.0001 0.001 0.01 0.1 1 10 100 1000 $\sigma = 0$ Tp[s]



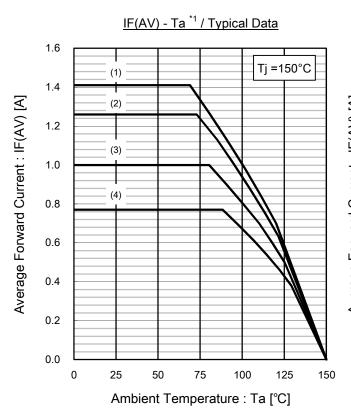
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### DB2G32500L1

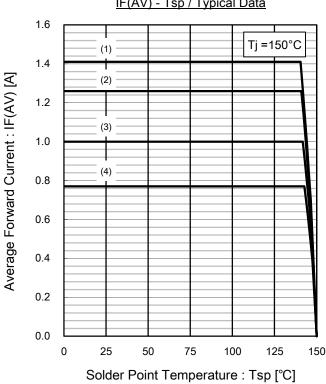
# **Panasonic**

# Power Derating Technical Data (Reference)



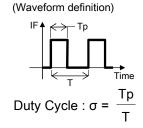
IF(AV) - Ta \*2 / Typical Data 1.6 Tj =150°C (1) 1.4 Average Forward Current: IF(AV) [A] (2) 1.2 (3) 1.0 (4) 8.0 0.6 0.4 0.2 0.0 25 50 75 150 100 125 Ambient Temperature : Ta [°C]

IF(AV) - Tsp / Typical Data



(Graph legends)				
(1)	σ = 1.0			
(2)	$\sigma = 0.8$			
(3)	$\sigma = 0.5$			

 $\sigma = 0.3$ 



(4)

\*1: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (108.6mm<sup>2</sup> area, 36µm thick).

(Evaluation board outline)



\*2: Device mounted on a FR4 PCB (25.4mm×25.4mm, 1mm thick), copper wiring (620.0mm<sup>2</sup> area, 36µm thick).

(Evaluation board outline)



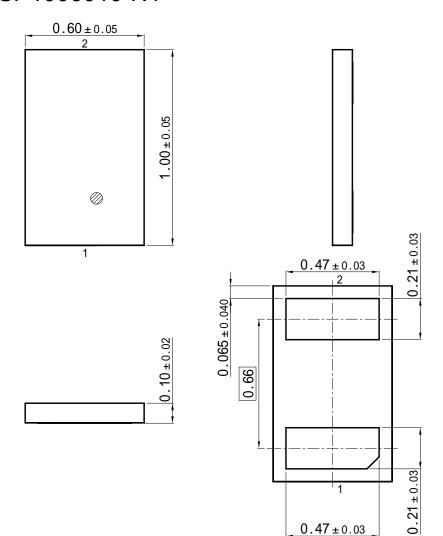
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Schottky Barrier Diode

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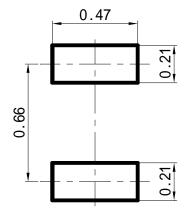
# DCSP1006010-N1

Unit: mm



■ Land Pattern (Reference)

Unit: mm



Established : 2015-10-13 Revised : ###-##-##

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